

Title (en)

USE OF A PARTICULATE MATERIAL COMPRISING A PARTICLE-SHAPED SYNTHETIC AMORPHIC SILICON DIOXIDE AS AN ADDITIVE FOR A MOLDING MATERIAL MIXTURE, CORRESPONDING METHOD, MIXTURES, AND KITS

Title (de)

VERWENDUNG EINES PARTIKULÄREN MATERIALS UMFASSEND EIN TEILCHENFÖRMIGES SYNTHETISCHES AMORPHES SILICIUMDIOXID ALS ADDITIV FÜR EINE FORMSTOFFMISCHUNG, ENTSPRECHENDE VERFAHREN, MISCHUNGEN UND KITS

Title (fr)

UTILISATION D'UN MATÉRIAU PARTICULAIRE COMPRENANT UN DIOXYDE DE SILICIUM AMORPHE SYNTHÉTIQUE SOUS FORME DE PARTICULES EN TANT QU'ADDITIF DESTINÉ À UN MÉLANGE DE MATIÈRE DE MOULAGE, AINSI QUE PROCÉDÉS, MÉLANGES ET KITS CORRESPONDANTS

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Application

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Abstract (en)

[origin: WO202229623A1] The invention relates to the use of a particulate material comprising a particle-shaped synthetic amorphous silicon dioxide having a particle size distribution with a median ranging from 0.1 to 0.4 μm , determined using laser diffraction, in the form of an individual component or one of a plurality of components as an additive for a molding material mixture, comprising at least: a refractory molding base material with an AFS grain fineness number ranging from 30 to 100, particulate amorphous silicon dioxide having a particle size distribution with a median ranging from 0.7 to 1.5 μm , determined using laser diffraction, and water glass in order to increase the moisture resistance of a molded body which can be produced by heat curing the molding body mixture. The invention also relates to corresponding methods, mixtures, and kits.

IPC 8 full level

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